

thermal management



pho**tronix**

technical data

Material types	AL1050/1100, AL5052-H34, AL6061-T6 series
Line width/spacing	Minimum 5 mil/5 mil (0.127 mm/0.127 mm). Base copper 1 oz
Soldermask Bridge	Minimum 5 mil (0.127 mm)
CNC V-cut	X-Y axis 30, 45, 60 degree, Inline V-cut, Jump V-cut
Countersunk hole size	T-type and V-type 0.7 mm at 1.6 mm board thickness
Maximum copper thickness	6 oz Cu
Finishing	Hot Air leveling, Immersion gold, Electro-plated gold, OSP.
Profiling	Punching, NC routing
Assembly	Hot Bar soldering, Reflow process
Solderpaste	Lead-free type, Leaded type

Using **Opulent®** patented IMS (Insulated Metal Substrate) technology, our solutions for thermal management allow the dissipation of heat away from critical components, to extend their working life and increase their efficiency. We can review your design for thermal efficiency and advise on changes and material selection to enhance the product's functionality.

We also offer a full LED assembly service at our bespoke facility located in Penang, Malaysia.

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